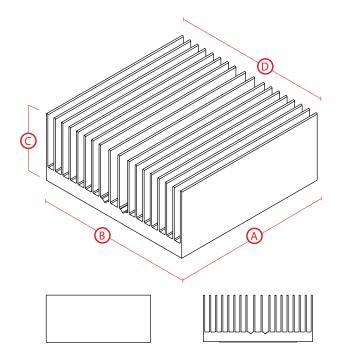


High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-54330D-C2-R0

Features & Benefits

- » High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- » Designed specifically for BGAs and other surface mount packages
- » Comes preassembled with high performance thermal interface material



Thermal Performance

*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	11.1	5	
300	1.5	8.1		
400	2.0	6.8		
500	2.5	6		
600	3.0	5.4		
700	3.5	5		
800	4.0	4.7		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
33 mm	33 mm	9.5 mm	33 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).